## HSP Types

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<td>SP</td>
<td>SP: Signal Processing, DSP Function-Specific</td>
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### DEVICE TYPE

- **43XXX**: Digital Filters
- **45XXX**: Signal Synthesis/Special Function
- **48XXX**: Image Processing
- **95XX**: Building Blocks
- **50XXX**: Freq. Conversion and Modulation/ Demodulation

### Package Designator

- **D**: Die
- **G**: Ceramic Pin Grid Array (CPGA)
- **J**: Plastic Leaded Chip Carrier (PLCC)
- **P**: Dual-In-Line Plastic (PDIP)
- **S**: Small Outline Plastic (SOIC)
- **V**: Metric Quad Flatpack (MQFP)
- **W**: Wafer

### HIGH-RELIABILITY DESIGNATOR

/883: -55°C to +125°C Fully Compliant to MIL-STD-883, Class B/QML

### Temperature Range

- **C**: Commercial, 0°C to +70°C
- **I**: Industrial, -40°C to +85°C
- **M**: Military, -55°C to +125°C

### Speed Grade in MHz

| NOTE: Suffix EV, EVAL: Evaluation Kit (Available for some products). |